

<b>PATENT ASSIGNMENT COVER SHEET</b>
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Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT4440325

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
CHANGYONG YU	05/10/2017
XIANLONG LIU	05/10/2017
YUETAO JIANG	05/10/2017
RUILING DOU	05/10/2017
BANGHUI LUO	05/10/2017
WALTER C. FORRESTER	05/10/2017
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	EMC IP HOLDING COMPANY LLC
<b>Street Address:</b>	176 SOUTH STREET
<b>City:</b>	HOPKINTON
<b>State/Country:</b>	MASSACHUSETTS
<b>Postal Code:</b>	01748
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15498834
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(508)366-4688
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	508-616-2900
<b>Email:</b>	Docket@BainwoodHuang.com
<b>Correspondent Name:</b>	BAINWOOD, HUANG & ASSOCIATES, LLC
<b>Address Line 1:</b>	2 CONNECTOR ROAD
<b>Address Line 4:</b>	WESTBOROUGH, MASSACHUSETTS 01581
<b>ATTORNEY DOCKET NUMBER:</b>	1003-496
<b>NAME OF SUBMITTER:</b>	BRUCE D. RUBENSTEIN, ESQ.
<b>SIGNATURE:</b>	/Bruce D. Rubenstein #39,349/
<b>DATE SIGNED:</b>	06/01/2017
<b>Total Attachments: 18</b>	

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source=1003-496-Inv6-executed-assignment-FORRESTER#page3.tif

**ASSIGNMENT**

**WHEREAS**, I, Changyong Yu, as the original inventor or an original joint inventor have invented an invention comprising and/or embodying certain improvements or discoveries or both as described in an application for Letters Patent of the United States entitled

**ENFORCING MINIMUM SPACE GUARANTEES IN THINLY-PROVISIONED FILE SYSTEMS**

which is further identified by Attorney Docket Number 1003-496;

**WHEREAS**, EMC IP Holding Company LLC (hereinafter "ASSIGNEE"), a limited liability company organized and existing under the laws of the state of Delaware and having a usual place of business at 176 South Street, Hopkinton, MA, 01748, USA, desires to acquire an interest therein in accordance with agreements duly entered into with me;

**NOW, THEREFORE**, to all whom it may concern be it known that for and in consideration of said agreements and of other good and valuable consideration, the receipt of which is hereby acknowledged, I have sold, assigned and transferred and by these presents do hereby sell, assign and transfer unto said ASSIGNEE, its successors, assigns and legal representatives, the entire right, title and interest in and throughout the United States of America, its territories and all foreign countries, in and to said invention as described in said application, together with the entire right, title and interest in and to said application and such Letters Patent as may issue thereon; said invention, application and Letters Patent to be held and enjoyed by said ASSIGNEE for its own use and behalf and for its successors, assigns and legal representatives, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held by me had this assignment and sale not been made; I hereby convey to ASSIGNEE all rights arising under or pursuant to any and all international agreements, treaties or laws relating to the protection of industrial property by filing any such applications for Letters Patent. I hereby acknowledge that this assignment, being of the entire right, title and interest in and to said invention, carries with it the right in ASSIGNEE to apply for and obtain from competent authorities in all countries of the world any and all Letters Patent by attorneys and agents of ASSIGNEE's selection and the right to procure the grant of all such Letters Patent to ASSIGNEE for its own name as assignee of the entire right, title and interest therein;

**AND**, I hereby further agree for myself and my executors and administrators to execute upon request any other lawful documents and likewise to perform any other

lawful acts which may be deemed necessary to secure fully the aforesaid invention to said ASSIGNEE, its successors, assigns and legal representatives, but at its or their expense and charges, including the execution of applications for patents in foreign countries, and the execution of substitution, reissue, divisional or continuation applications and preliminary or other statements and the giving of testimony in any interference or other proceeding in which said invention or any application or patent directed thereto may be involved;

**AND**, I do hereby authorize and request the Commissioner of Patents of the United States to issue such Letters Patent as shall be granted upon said application or applications based thereon to said ASSIGNEE, its successors, assigns, and legal representatives;

**AND** I hereby authorize the attorneys at Bainwood Huang & Associates LLC to insert here in parentheses

( 15/498,834 , filed April 27, 2013 )

the application number and filing date of said application (or foreign counterpart application) to facilitate the recording or other official processing of this Assignment.

Date: May 10, 2017

Changyong Yu

Inventor's Signature

Legal name of inventor:

Changyong Yu

Residence:

No. 501, Building 36  
No. 925, Shangzhong Road West  
Minhang District  
Shanghai, 200237  
China (People's Republic)

Mailing Address:

Same as above

Citizenship:

CN[BDR1]

I Ying Huang (name) whose residential address is  
NO. 95, Chifeng Road, Yangpu District, Shanghai - China

was personally present and did see Changyong Yu (name of person signing the assignment) who is personally known to me, execute the above assignment.

Ying Huang (signature of first witness)

Signed at KIC1, NO. 252, Songhu Road, Yangpu District, Shanghai (location of witness signature)

on this day 10th, May of 2017. (date of signature)

I Jun Liu (name) whose residential address is  
NO. 18th, Huailiang RD, Jiading District, Shanghai

was personally present and did see Changyong Yu (name of person signing the assignment) who is personally known to me, execute the above assignment.

Jun Liu (signature of second witness)

Signed at KIC1, NO. 252, Songhu RD, Yangpu District, Shanghai (location of witness signature)

on this day 10th, May of 2017. (date of signature)

PATENT ASSIGNMENT  
Attorney Docket No.: 1003-496  
Client Docket No.: EMC-16-1065

**ASSIGNMENT**

**WHEREAS**, I, Xianlong Liu, as the original inventor or an original joint inventor have invented an invention comprising and/or embodying certain improvements or discoveries or both as described in an application for Letters Patent of the United States entitled

**ENFORCING MINIMUM SPACE GUARANTEES IN THINLY-PROVISIONED FILE SYSTEMS**

which is further identified by Attorney Docket Number 1003-496;

**WHEREAS**, EMC IP Holding Company LLC (hereinafter "ASSIGNEE"), a limited liability company organized and existing under the laws of the state of Delaware and having a usual place of business at 176 South Street, Hopkinton, MA, 01748, USA, desires to acquire an interest therein in accordance with agreements duly entered into with me;

**NOW, THEREFORE**, to all whom it may concern be it known that for and in consideration of said agreements and of other good and valuable consideration, the receipt of which is hereby acknowledged, I have sold, assigned and transferred and by these presents do hereby sell, assign and transfer unto said ASSIGNEE, its successors, assigns and legal representatives, the entire right, title and interest in and throughout the United States of America, its territories and all foreign countries, in and to said invention as described in said application, together with the entire right, title and interest in and to said application and such Letters Patent as may issue thereon; said invention, application and Letters Patent to be held and enjoyed by said ASSIGNEE for its own use and behalf and for its successors, assigns and legal representatives, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held by me had this assignment and sale not been made; I hereby convey to ASSIGNEE all rights arising under or pursuant to any and all international agreements, treaties or laws relating to the protection of industrial property by filing any such applications for Letters Patent. I hereby acknowledge that this assignment, being of the entire right, title and interest in and to said invention, carries with it the right in ASSIGNEE to apply for and obtain from competent authorities in all countries of the world any and all Letters Patent by attorneys and agents of ASSIGNEE's selection and the right to procure the grant of all such Letters Patent to ASSIGNEE for its own name as assignee of the entire right, title and interest therein;

**AND**, I hereby further agree for myself and my executors and administrators to execute upon request any other lawful documents and likewise to perform any other

lawful acts which may be deemed necessary to secure fully the aforesaid invention to said ASSIGNEE, its successors, assigns and legal representatives, but at its or their expense and charges, including the execution of applications for patents in foreign countries, and the execution of substitution, reissue, divisional or continuation applications and preliminary or other statements and the giving of testimony in any interference or other proceeding in which said invention or any application or patent directed thereto may be involved;

**AND**, I do hereby authorize and request the Commissioner of Patents of the United States to issue such Letters Patent as shall be granted upon said application or applications based thereon to said ASSIGNEE, its successors, assigns, and legal representatives;

**AND** I hereby authorize the attorneys at Bainwood Huang & Associates LLC to insert here in parentheses

(15/498, 834 , filed April 27, 2017 )

the application number and filing date of said application (or foreign counterpart application) to facilitate the recording or other official processing of this Assignment.

Date: May 10, 2017

Xianlong Liu  
Inventor's Signature

Legal name of inventor: Xianlong Liu  
Residence: Room 502, No. 16, Lane 777, Linghe Road  
Pudong District  
Shanghai, 200129  
China (People's Republic)  
Mailing Address: Same as above  
Citizenship: CN<sub>[BDR1]</sub>

I Jun Liu (name) whose residential address is  
NO. 18th, Hua Jiang RD, Tiading District, Shanghai  
was personally present and did see Xianlong Liu (name of person signing the  
assignment) who is personally known to me, execute the above assignment.

Jun Liu (signature of first witness)

Signed at KIC1, NO. 252, Songhu RD, Shanghai (location of witness signature)

on this day 10th, May of 2017. (date of signature)

I Xing Huang (name) whose residential address is  
NO. 95 chifeng Road, Yangpu District, Shanghai  
was personally present and did see Xianlong Liu (name of person signing the  
assignment) who is personally known to me, execute the above assignment.

Xing Huang (signature of second witness)

Signed at KIC1, NO. 252, Songhu Road, Shanghai (location of witness signature)

on this day 10th May of 2017. (date of signature)



**ASSIGNMENT**

**WHEREAS**, I, Yuetao Jiang, as the original inventor or an original joint inventor have invented an invention comprising and/or embodying certain improvements or discoveries or both as described in an application for Letters Patent of the United States entitled

**ENFORCING MINIMUM SPACE GUARANTEES IN THINLY-PROVISIONED FILE SYSTEMS**

which is further identified by Attorney Docket Number 1003-496;

**WHEREAS**, EMC IP Holding Company LLC (hereinafter "ASSIGNEE"), a limited liability company organized and existing under the laws of the state of Delaware and having a usual place of business at 176 South Street, Hopkinton, MA, 01748, USA, desires to acquire an interest therein in accordance with agreements duly entered into with me;

**NOW, THEREFORE**, to all whom it may concern be it known that for and in consideration of said agreements and of other good and valuable consideration, the receipt of which is hereby acknowledged, I have sold, assigned and transferred and by these presents do hereby sell, assign and transfer unto said ASSIGNEE, its successors, assigns and legal representatives, the entire right, title and interest in and throughout the United States of America, its territories and all foreign countries, in and to said invention as described in said application, together with the entire right, title and interest in and to said application and such Letters Patent as may issue thereon; said invention, application and Letters Patent to be held and enjoyed by said ASSIGNEE for its own use and behalf and for its successors, assigns and legal representatives, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held by me had this assignment and sale not been made; I hereby convey to ASSIGNEE all rights arising under or pursuant to any and all international agreements, treaties or laws relating to the protection of industrial property by filing any such applications for Letters Patent. I hereby acknowledge that this assignment, being of the entire right, title and interest in and to said invention, carries with it the right in ASSIGNEE to apply for and obtain from competent authorities in all countries of the world any and all Letters Patent by attorneys and agents of ASSIGNEE's selection and the right to procure the grant of all such Letters Patent to ASSIGNEE for its own name as assignee of the entire right, title and interest therein;

**AND**, I hereby further agree for myself and my executors and administrators to execute upon request any other lawful documents and likewise to perform any other

PATENT ASSIGNMENT  
Attorney Docket No.: 1003-496  
Client Docket No.: EMC-16-1065

lawful acts which may be deemed necessary to secure fully the aforesaid invention to said ASSIGNEE, its successors, assigns and legal representatives, but at its or their expense and charges, including the execution of applications for patents in foreign countries, and the execution of substitution, reissue, divisional or continuation applications and preliminary or other statements and the giving of testimony in any interference or other proceeding in which said invention or any application or patent directed thereto may be involved;

**AND**, I do hereby authorize and request the Commissioner of Patents of the United States to issue such Letters Patent as shall be granted upon said application or applications based thereon to said ASSIGNEE, its successors, assigns, and legal representatives;

**AND** I hereby authorize the attorneys at Bainwood Huang & Associates LLC to insert here in parentheses

( 15/498834 , filed April 27, 2017 )

the application number and filing date of said application (or foreign counterpart application) to facilitate the recording or other official processing of this Assignment.

Date: 2017.5.10

Yuetao Jiang  
Inventor's Signature

Legal name of inventor: Yuetao Jiang  
Residence: No. 87 East Minzhu Street, NanXiang  
Shanghai, 201802  
China (People's Republic)  
Mailing Address: Same as above  
Citizenship: CN<sub>[BOR:1]</sub>

I Frankie, Feng (name) whose residential address is  
2nd floor, Building 1, Songhu Road, Yangpu District, Shanghai  
was personally present and did see Yuetao Jiang (name of person signing the  
assignment) who is personally known to me, execute the above assignment.

Frankie, Feng (signature of first witness)  
Signed at KIC 1 (location of witness signature)  
on this day 5, 10 of 2017. (date of signature)

I Patrick Lu (name) whose residential address is  
3rd floor Building 1, Songhu Road, Yangpu District, Shanghai  
was personally present and did see Yuetao Jiang (name of person signing the  
assignment) who is personally known to me, execute the above assignment.

Patrick Lu (signature of second witness)  
Signed at KIC 1 (location of witness signature)  
on this day 5, 10 of 2017. (date of signature)

**ASSIGNMENT**

**WHEREAS**, I, Ruiling Dou, as the original inventor or an original joint inventor have invented an invention comprising and/or embodying certain improvements or discoveries or both as described in an application for Letters Patent of the United States entitled

**ENFORCING MINIMUM SPACE GUARANTEES IN THINLY-PROVISIONED FILE SYSTEMS**

which is further identified by Attorney Docket Number 1003-496;

**WHEREAS**, EMC IP Holding Company LLC (hereinafter "ASSIGNEE"), a limited liability company organized and existing under the laws of the state of Delaware and having a usual place of business at 176 South Street, Hopkinton, MA, 01748, USA, desires to acquire an interest therein in accordance with agreements duly entered into with me;

**NOW, THEREFORE**, to all whom it may concern be it known that for and in consideration of said agreements and of other good and valuable consideration, the receipt of which is hereby acknowledged, I have sold, assigned and transferred and by these presents do hereby sell, assign and transfer unto said ASSIGNEE, its successors, assigns and legal representatives, the entire right, title and interest in and throughout the United States of America, its territories and all foreign countries, in and to said invention as described in said application, together with the entire right, title and interest in and to said application and such Letters Patent as may issue thereon; said invention, application and Letters Patent to be held and enjoyed by said ASSIGNEE for its own use and behalf and for its successors, assigns and legal representatives, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held by me had this assignment and sale not been made; I hereby convey to ASSIGNEE all rights arising under or pursuant to any and all international agreements, treaties or laws relating to the protection of industrial property by filing any such applications for Letters Patent. I hereby acknowledge that this assignment, being of the entire right, title and interest in and to said invention, carries with it the right in ASSIGNEE to apply for and obtain from competent authorities in all countries of the world any and all Letters Patent by attorneys and agents of ASSIGNEE's selection and the right to procure the grant of all such Letters Patent to ASSIGNEE for its own name as assignee of the entire right, title and interest therein;

**AND**, I hereby further agree for myself and my executors and administrators to execute upon request any other lawful documents and likewise to perform any other

lawful acts which may be deemed necessary to secure fully the aforesaid invention to said ASSIGNEE, its successors, assigns and legal representatives, but at its or their expense and charges, including the execution of applications for patents in foreign countries, and the execution of substitution, reissue, divisional or continuation applications and preliminary or other statements and the giving of testimony in any interference or other proceeding in which said invention or any application or patent directed thereto may be involved;

**AND**, I do hereby authorize and request the Commissioner of Patents of the United States to issue such Letters Patent as shall be granted upon said application or applications based thereon to said ASSIGNEE, its successors, assigns, and legal representatives;

**AND** I hereby authorize the attorneys at Bainwood Huang & Associates LLC to insert here in parentheses

(15/498,834 , filed April 27, 2017 )

the application number and filing date of said application (or foreign counterpart application) to facilitate the recording or other official processing of this Assignment.

Date: 2017/05/10

Dou Ruiling  
Inventor's Signature

Legal name of inventor: Ruiling Dou  
Residence: 478 FangHua Road  
Shanghai, Shanghai  
China (People's Republic)  
Mailing Address: Same as above  
Citizenship: CN<sub>(BDR)</sub>

I Jun Liu (name) whose residential address is  
NO.18, HuaJiang RD, Jiading District, Shanghai, China  
was personally present and did see Ruiling Dou (name of person signing the  
assignment) who is personally known to me, execute the above assignment.

Jun Liu (signature of first witness)

Signed at KIL1, Yangpu District, Shanghai (location of witness signature)

on this day 10th, May of 2017. (date of signature)

I Ying Huang (name) whose residential address is  
NO.95, chiFeng Road, Yangpu District, Shanghai, China  
was personally present and did see Ruiling Dou (name of person signing the  
assignment) who is personally known to me, execute the above assignment.

Ying Huang (signature of second witness)

Signed at KIL1, Yangpu District, Shanghai (location of witness signature)

on this day 10th, May of 2017. (date of signature)

**ASSIGNMENT**

**WHEREAS**, I, Banghui Luo, as the original inventor or an original joint inventor have invented an invention comprising and/or embodying certain improvements or discoveries or both as described in an application for Letters Patent of the United States entitled

**ENFORCING MINIMUM SPACE GUARANTEES IN THINLY-PROVISIONED FILE SYSTEMS**

which is further identified by Attorney Docket Number 1003-496;

**WHEREAS**, EMC IP Holding Company LLC (hereinafter "ASSIGNEE"), a limited liability company organized and existing under the laws of the state of Delaware and having a usual place of business at 176 South Street, Hopkinton, MA, 01748, USA, desires to acquire an interest therein in accordance with agreements duly entered into with me;

**NOW, THEREFORE**, to all whom it may concern be it known that for and in consideration of said agreements and of other good and valuable consideration, the receipt of which is hereby acknowledged, I have sold, assigned and transferred and by these presents do hereby sell, assign and transfer unto said ASSIGNEE, its successors, assigns and legal representatives, the entire right, title and interest in and throughout the United States of America, its territories and all foreign countries, in and to said invention as described in said application, together with the entire right, title and interest in and to said application and such Letters Patent as may issue thereon; said invention, application and Letters Patent to be held and enjoyed by said ASSIGNEE for its own use and behalf and for its successors, assigns and legal representatives, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held by me had this assignment and sale not been made; I hereby convey to ASSIGNEE all rights arising under or pursuant to any and all international agreements, treaties or laws relating to the protection of industrial property by filing any such applications for Letters Patent. I hereby acknowledge that this assignment, being of the entire right, title and interest in and to said invention, carries with it the right in ASSIGNEE to apply for and obtain from competent authorities in all countries of the world any and all Letters Patent by attorneys and agents of ASSIGNEE's selection and the right to procure the grant of all such Letters Patent to ASSIGNEE for its own name as assignee of the entire right, title and interest therein;

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AND, I do hereby authorize and request the Commissioner of Patents of the United States to issue such Letters Patent as shall be granted upon said application or applications based thereon to said ASSIGNEE, its successors, assigns, and legal representatives;

AND I hereby authorize the attorneys at Bainwood Huang & Associates LLC to insert here in parentheses

(15/498,834, filed April 27, 2017

the application number and filing date of said application (or foreign counterpart application) to facilitate the recording or other official processing of this Assignment.



Date: 05/10/2017

Banghui Luo  
Inventor's Signature

Legal name of inventor: Banghui Luo  
Residence: 2053 Huangxing Road  
Building 1, Room 502  
Yangpu District  
Shanghai, 200237  
China (People's Republic)  
Mailing Address: Same as above  
Citizenship: CN

I Xing Huang (name) whose residential address is  
No. 95 Chifeng Road, Yangpu District, Shanghai

was personally present and did see Banghui Luo (name of person signing the assignment) who is personally known to me, execute the above assignment.

Xing Huang (signature of first witness)

Signed at KTC1, NO. 252, Songhu Road, Shanghai (location of witness signature)

on this day 10th May of 2017. (date of signature)

I Jun Lin (name) whose residential address is  
NO. 187th, Huaqiang RD, Jiading District, Shanghai

was personally present and did see Banghui Luo (name of person signing the assignment) who is personally known to me, execute the above assignment.

Jun Lin (signature of second witness)

Signed at KTC1, NO. 252, Songhu RD, Shanghai (location of witness signature)

on this day 10th, May of 2017. (date of signature)

**ASSIGNMENT**

**WHEREAS**, I, Walter C. Forrester, as the original inventor or an original joint inventor have invented an invention comprising and/or embodying certain improvements or discoveries or both as described in an application for Letters Patent of the United States entitled

**ENFORCING MINIMUM SPACE GUARANTEES IN THINLY-PROVISIONED FILE SYSTEMS**

which is further identified by Attorney Docket Number 1003-496;

**WHEREAS**, EMC IP Holding Company LLC (hereinafter "ASSIGNEE"), a limited liability company organized and existing under the laws of the state of Delaware and having a usual place of business at 176 South Street, Hopkinton, MA, 01748, USA, desires to acquire an interest therein in accordance with agreements duly entered into with me;

**NOW, THEREFORE**, to all whom it may concern be it known that for and in consideration of said agreements and of other good and valuable consideration, the receipt of which is hereby acknowledged, I have sold, assigned and transferred and by these presents do hereby sell, assign and transfer unto said ASSIGNEE, its successors, assigns and legal representatives, the entire right, title and interest in and throughout the United States of America, its territories and all foreign countries, in and to said invention as described in said application, together with the entire right, title and interest in and to said application and such Letters Patent as may issue thereon; said invention, application and Letters Patent to be held and enjoyed by said ASSIGNEE for its own use and behalf and for its successors, assigns and legal representatives, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held by me had this assignment and sale not been made; I hereby convey to ASSIGNEE all rights arising under or pursuant to any and all international agreements, treaties or laws relating to the protection of industrial property by filing any such applications for Letters Patent. I hereby acknowledge that this assignment, being of the entire right, title and interest in and to said invention, carries with it the right in ASSIGNEE to apply for and obtain from competent authorities in all countries of the world any and all Letters Patent by attorneys and agents of ASSIGNEE's selection and the right to procure the grant of all such Letters Patent to ASSIGNEE for its own name as assignee of the entire right, title and interest therein;

**AND**, I hereby further agree for myself and my executors and administrators to execute upon request any other lawful documents and likewise to perform any other

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**AND**, I do hereby authorize and request the Commissioner of Patents of the United States to issue such Letters Patent as shall be granted upon said application or applications based thereon to said ASSIGNEE, its successors, assigns, and legal representatives;

**AND** I hereby authorize the attorneys at Bainwood Huang & Associates LLC to insert here in parentheses

(15/498,834 , filed April 27, 2017 )

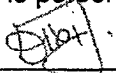
the application number and filing date of said application (or foreign counterpart application) to facilitate the recording or other official processing of this Assignment.

Date: 5/10/17

  
\_\_\_\_\_  
Inventor's Signature

Legal name of inventor: Walter C. Forrester  
Residence: 21 Magnum Court  
Berkeley Heights, NJ 07922  
United States of America  
Mailing Address: Same as above  
Citizenship: US

I Dixit Patel (name) whose residential address is  
217 Morning Glory Dr. Monroe, NJ-08831,  
was personally present and did see Walter C. Forrester (name of person signing the  
assignment) who is personally known to me, execute the above assignment.

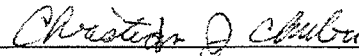
  
\_\_\_\_\_  
(signature of first witness)

Signed at Warren, NJ (location of witness signature)

on this day 10<sup>th</sup> of May of 2017. (date of signature)

---

I Christian J Chuka (name) whose residential address is  
25 Hamilton Ave, Berkeley Hts, NJ 07922,  
was personally present and did see Walter C. Forrester (name of person signing the  
assignment) who is personally known to me, execute the above assignment.

  
\_\_\_\_\_  
(signature of second witness)

Signed at Warren, NJ (location of witness signature)

on this day May 10 of 2017. (date of signature)